

ABSTRACT

A method of laser micro-machining a work piece, with a laser, including the steps of: locating the workpiece on a carrier forming a part of a transport system, the carrier can be displaced along a path parallel to an X-axis of the workpiece, a Y-axis lying transverse the path, and a Z-axis lying transverse the path; focussing an image generated by an output beam from the laser at a working datum position defined relative to the path which path is established by the transport system to traverse the first datum position; a plane defined by the X- and Y- axis lying substantially perpendicular to the output beam; and displacing the workpiece along the path by way of the transport system so as to enable the work-piece to be subject to micro-machining by way of the laser.